

GENERAL DESCRIPTION

The 74HC164 is an 8-bit serial-in and parallel-out shift register which can accept a wide supply voltage range from 2.0V to 5.5V.

This device provides gated serial inputs (DSA and DSB) and parallel data outputs (Q0 to Q7). DSA and DSB support serial data entry, where either input can allow data to enter through another input as an active-high input. CP is a clock input. When the device is on low-to-high clock transition of the CP, data can be shifted. \overline{MR} is the master reset input that is separated from the other inputs. When \overline{MR} is held low, it can make the register clear and all outputs must be low level. The clamp diodes of inputs allow the use of current limiting resistors to connect inputs to the voltage exceeding supply voltage.

The 74HC164 is available in Green SOIC-14 and TSSOP-14 packages. It operates over an operating temperature range of -40°C to +125°C.

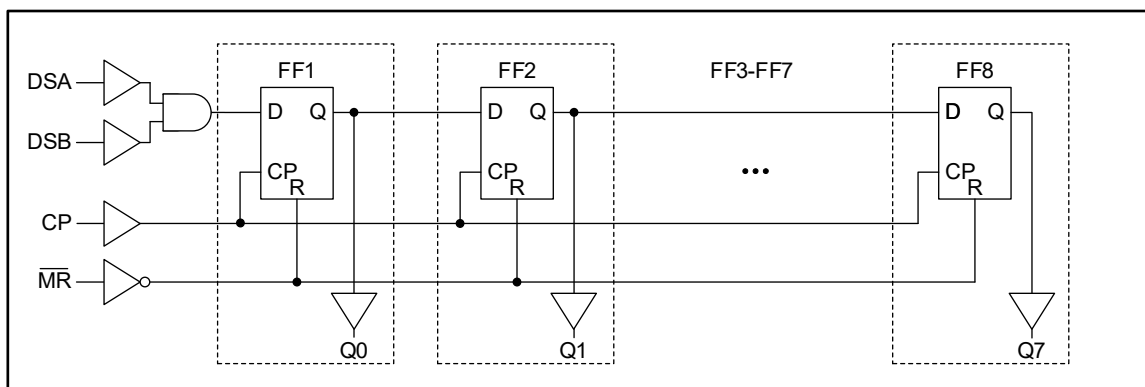
FEATURES

- **Wide Operating Voltage Range: 2.0V to 5.5V**
- **+5.2mA/-5.2mA Output Current**
- **CMOS Low Power Consumption**
- **Gated Serial Data Inputs**
- **Asynchronous Master Reset Input**
- **-40°C to +125°C Operating Temperature Range**
- **Available in Green SOIC-14 and TSSOP-14 Packages**

APPLICATIONS

Servers and I/O Expanders
LED Displays

LOGIC DIAGRAM



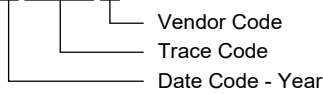
PACKAGE/ORDERING INFORMATION

| MODEL | PACKAGE DESCRIPTION | SPECIFIED TEMPERATURE RANGE | ORDERING NUMBER | PACKAGE MARKING | PACKING OPTION |
|---------|---------------------|-----------------------------|------------------|---------------------------|---------------------|
| 74HC164 | SOIC-14 | -40°C to +125°C | 74HC164XS14G/TR | 74HC164XS14 XXXXX | Tape and Reel, 2500 |
| | TSSOP-14 | -40°C to +125°C | 74HC164XTS14G/TR | 74HC164 XTS14 XXXXX | Tape and Reel, 4000 |

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

XXXXX



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾

| | |
|---|--------------------------------------|
| Supply Voltage Range, V_{CC} | -0.5V to 7.0V |
| Input Voltage Range, V_I ⁽²⁾ | -0.5V to MIN(7.0V, $V_{CC} + 0.5V$) |
| Output Voltage Range, V_O ⁽²⁾ | -0.5V to MIN(7.0V, $V_{CC} + 0.5V$) |
| Input Clamp Current, I_{IK} ($V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$) | ±20mA |
| Output Clamp Current, I_{OK} ($V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$) | ±20mA |
| Continuous Output Current, I_O ($-0.5V < V_O < V_{CC} + 0.5V$) | ±25mA |
| Continuous Current through V_{CC} or GND..... | ±50mA |
| Junction Temperature ⁽³⁾ | +150°C |
| Storage Temperature Range | -65°C to +150°C |
| Lead Temperature (Soldering, 10s)..... | +260°C |
| ESD Susceptibility | |
| HBM..... | 6000V |
| CDM | 1000V |

RECOMMENDED OPERATING CONDITIONS

| | |
|---|-----------------|
| Supply Voltage Range, V_{CC} | 2.0V to 5.5V |
| Input Voltage Range, V_I | 0V to V_{CC} |
| Output Voltage Range, V_O | 0V to V_{CC} |
| Output Current, I_O | ±5.2mA |
| Input Transition Rise or Fall Rate, $\Delta t/\Delta V$ | |
| $V_{CC} = 2.0V$ | 625ns/V (MAX) |
| $V_{CC} = 4.5V$ | 139ns/V (MAX) |
| $V_{CC} = 5.5V$ | 83ns/V (MAX) |
| Operating Temperature Range | -40°C to +125°C |

OVERSTRESS CAUTION

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.
2. The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.
3. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

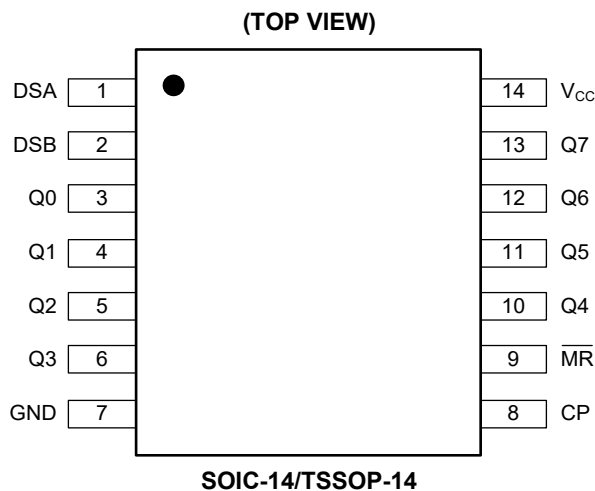
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATIONS



PIN DESCRIPTION

| PIN | NAME | FUNCTION |
|----------------------------|--------------------------------|---|
| 1 | DSA | Serial Data Input A. |
| 2 | DSB | Serial Data Input B. |
| 3, 4, 5, 6, 10, 11, 12, 13 | Q0, Q1, Q2, Q3, Q4, Q5, Q6, Q7 | Parallel Data Outputs. |
| 7 | GND | Ground. |
| 8 | CP | Clock Input (Low-to-High Clock Transition, Edge-Triggered). |
| 9 | $\overline{\text{MR}}$ | Master Reset Input (Active-Low). |
| 14 | V _{CC} | Supply Voltage. |

FUNCTION TABLE

| INPUT | | | | OUTPUT | |
|------------------------|----|-----|-----|--------|----------|
| $\overline{\text{MR}}$ | CP | DSA | DSB | Q0 | Q1 to Q7 |
| L | X | X | X | L | L to L |
| H | ↑ | l | l | L | q0 to q6 |
| H | ↑ | l | h | L | q0 to q6 |
| H | ↑ | h | l | L | q0 to q6 |
| H | ↑ | h | h | H | q0 to q6 |

H = High voltage level.

h = High voltage level one setup time before clock rising edge ↑.

L = Low voltage level.

l = Low voltage level one setup time before clock rising edge ↑.

q = The state of the referenced output one setup time before clock rising edge ↑.

↑ = Low-to-high clock transition.

X = Don't care.

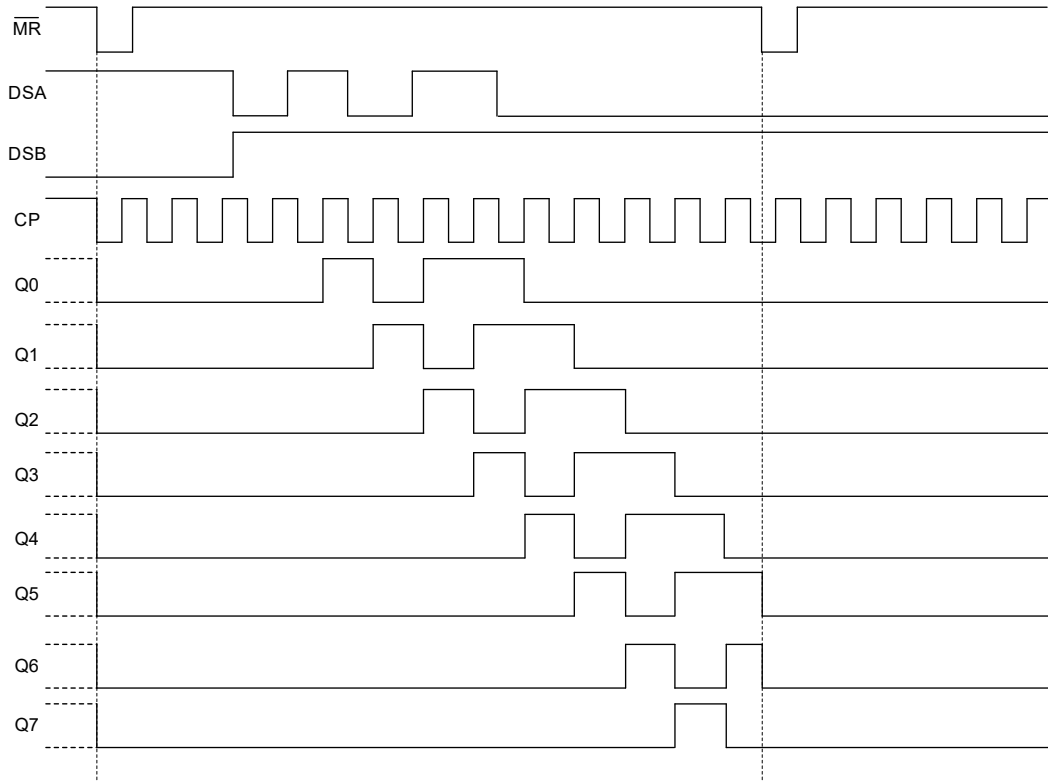


Figure 1. Timing Diagram

ELECTRICAL CHARACTERISTICS(Full = -40°C to +125°C, all typical values are measured at T_A = +25°C, unless otherwise noted.)

| PARAMETER | SYMBOL | CONDITIONS | TEMP | MIN | TYP | MAX | UNITS |
|---------------------------|-----------------|--|-------|------|-------|------|-------|
| High-Level Input Voltage | V _{IH} | V _{CC} = 2.0V | Full | 1.50 | | | V |
| | | V _{CC} = 4.5V | Full | 3.15 | | | |
| | | V _{CC} = 5.5V | Full | 3.85 | | | |
| Low-Level Input Voltage | V _{IL} | V _{CC} = 2.0V | Full | | | 0.50 | V |
| | | V _{CC} = 4.5V | Full | | | 1.35 | |
| | | V _{CC} = 5.5V | Full | | | 1.65 | |
| High-Level Output Voltage | V _{OH} | V _{CC} = 2.0V, I _O = -20μA | Full | 1.95 | 1.995 | | V |
| | | V _{CC} = 4.5V, I _O = -20μA | Full | 4.45 | 4.495 | | |
| | | V _{CC} = 5.5V, I _O = -20μA | Full | 5.45 | 5.495 | | |
| | | V _{CC} = 4.5V, I _O = -4.0mA | Full | 3.84 | 4.390 | | |
| | | V _{CC} = 5.5V, I _O = -5.2mA | Full | 4.84 | 5.380 | | |
| Low-Level Output Voltage | V _{OL} | V _{CC} = 2.0V, I _O = 20μA | Full | | 0.005 | 0.05 | V |
| | | V _{CC} = 4.5V, I _O = 20μA | Full | | 0.005 | 0.05 | |
| | | V _{CC} = 5.5V, I _O = 20μA | Full | | 0.005 | 0.05 | |
| | | V _{CC} = 4.5V, I _O = 4.0mA | Full | | 0.10 | 0.33 | |
| | | V _{CC} = 5.5V, I _O = 5.2mA | Full | | 0.12 | 0.33 | |
| Input Leakage Current | I _I | V _{CC} = 5.5V, V _I = V _{CC} or GND | Full | | | ±1 | μA |
| Supply Current | I _{CC} | V _{CC} = 5.5V, V _I = V _{CC} or GND, I _O = 0A | Full | | | 10 | μA |
| Input Capacitance | C _I | | +25°C | | 4 | | pF |

DYNAMIC CHARACTERISTICS

(See Figure 2 for test circuit. Full = -40°C to +125°C, all typical values are measured at $C_L = 50\text{pF}$ and $T_A = +25^\circ\text{C}$, unless otherwise noted.)

| PARAMETER | SYMBOL | CONDITIONS | TEMP | MIN ⁽¹⁾ | TYP | MAX ⁽¹⁾ | UNITS | |
|--|-----------|---|------------------------|--------------------|-----|--------------------|-------|-----|
| Propagation Delay ⁽²⁾ | t_{PD} | CP to Qn, see Figure 3 | $V_{CC} = 2.0\text{V}$ | Full | 7 | 30 | 100 | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 4 | 11 | 30 | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 3 | 10 | 25 | |
| High-to-Low Propagation Delay | t_{PHL} | $\overline{\text{MR}}$ to Qn, see Figure 4 | $V_{CC} = 2.0\text{V}$ | Full | 7 | 24 | 100 | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 4 | 10 | 30 | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 4 | 9 | 25 | |
| Transition Time ⁽²⁾ | t_T | See Figure 3 | $V_{CC} = 2.0\text{V}$ | Full | 1.5 | 17 | 40 | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 0.3 | 6 | 18 | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 0.3 | 4 | 15 | |
| Pulse Width | t_W | CP high or low, see Figure 3 | $V_{CC} = 2.0\text{V}$ | Full | 50 | | | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 22 | | | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 20 | | | |
| | | $\overline{\text{MR}}$ low, see Figure 4 | $V_{CC} = 2.0\text{V}$ | Full | 50 | | | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 22 | | | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 20 | | | |
| Recovery Time | t_{REC} | $\overline{\text{MR}}$ to CP, see Figure 4 | $V_{CC} = 2.0\text{V}$ | Full | 30 | | | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 15 | | | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 14 | | | |
| Setup Time | t_{SU} | DSA, DSB to CP, see Figure 5 | $V_{CC} = 2.0\text{V}$ | Full | 30 | | | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 15 | | | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 14 | | | |
| Hold Time | t_H | DSA, DSB to CP, see Figure 5 | $V_{CC} = 2.0\text{V}$ | Full | 4 | | | ns |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 4 | | | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 4 | | | |
| Maximum Frequency | f_{MAX} | CP, see Figure 3 | $V_{CC} = 2.0\text{V}$ | Full | 4 | | | MHz |
| | | | $V_{CC} = 4.5\text{V}$ | Full | 20 | | | |
| | | | $V_{CC} = 5.5\text{V}$ | Full | 24 | | | |
| Power Dissipation Capacitance ⁽³⁾ | C_{PD} | Per package, $V_I = \text{GND to } V_{CC}$ | +25°C | | 45 | | pF | |

NOTES:

- Specified by design and characterization, not production tested.
- t_{PD} is the same as t_{PLH} and t_{PHL} . t_T is the same as t_{THL} and t_{TLH} .
- C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_{DS} \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$$

where:

f_{DS} = Input frequency in MHz.

f_o = Output frequency in MHz.

$f_{CP} = 2 \times f_{DS}$

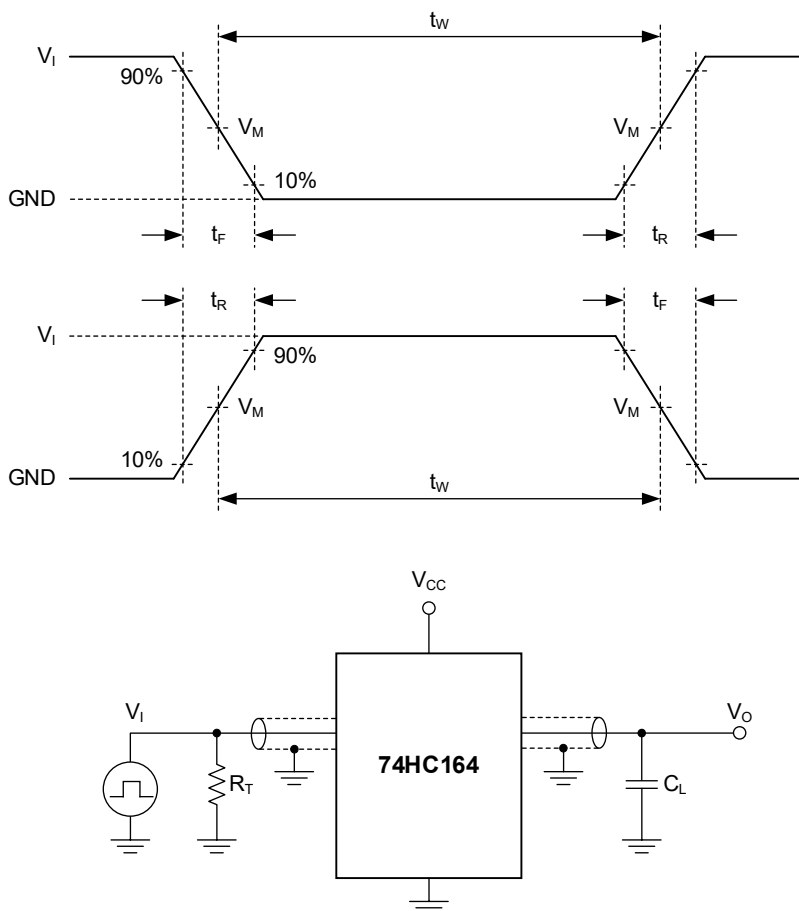
C_L = Output load capacitance in pF.

V_{CC} = Supply voltage in Volts.

N = Number of inputs switching.

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = Sum of the outputs.

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

C_L : Load capacitance (includes jig and probe).

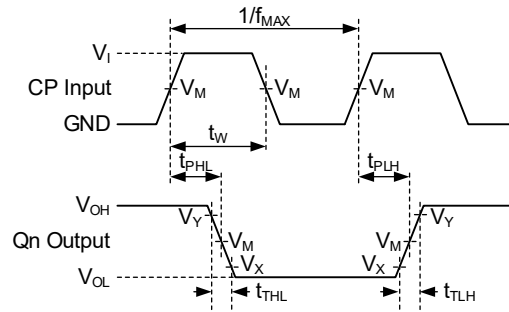
R_T : Termination resistance (equals to output impedance Z_O of the pulse generator).

Figure 2. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

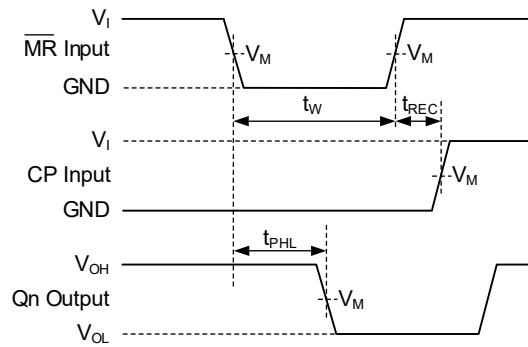
| SUPPLY VOLTAGE | INPUT | | LOAD | TEST |
|----------------|----------|--------------|-------|--------------------|
| V_{CC} | V_I | t_R, t_F | C_L | |
| 2.0V to 5.5V | V_{CC} | $\leq 6.0ns$ | 50pF | t_{PHL}, t_{PLH} |

WAVEFORMS



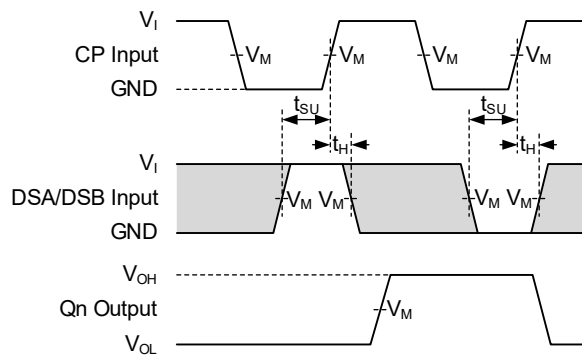
Test conditions are given in Table 1.
 Measurement points are given in Table 2.
 Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load

Figure 3. Clock Input to Output Propagation Delays, Clock Pulse Width, Transition Times and Maximum Frequency



Test conditions are given in Table 1.
 Measurement points are given in Table 2.
 Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 4. Master Reset Input to Output Propagation Delays, Pulse Width and Recovery Time



Test conditions are given in Table 1.
 Measurement points are given in Table 2.
 Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.
 The shaded areas refer to when the input is allowed to change for predictable output performance.

Figure 5. Data Setup and Hold Times

WAVEFORMS (continued)

Table 2. Measurement Points

| SUPPLY VOLTAGE | INPUT | | OUTPUT | | |
|----------------|----------|---------------------|---------------------|---------------------|---------------------|
| V_{CC} | V_I | $V_M^{(1)}$ | V_M | V_X | V_Y |
| 2.0V to 5.5V | V_{CC} | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | $0.1 \times V_{CC}$ | $0.9 \times V_{CC}$ |

NOTE:

1. The measurement points should be V_{IH} or V_{IL} when the input rising or falling time exceeds 6.0ns.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

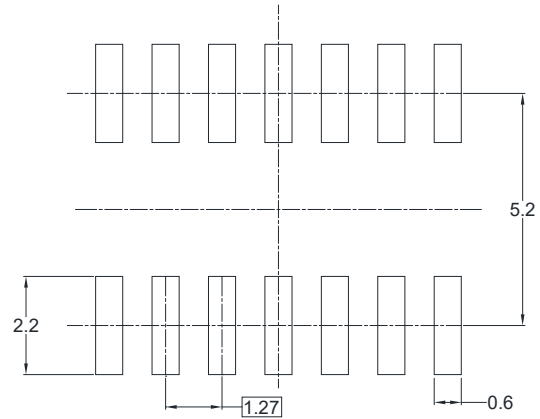
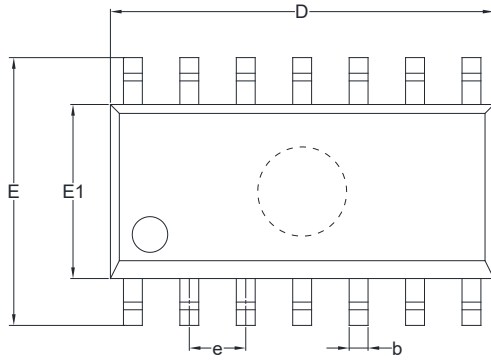
| JULY 2024 – REV.A to REV.A.1 | Page |
|------------------------------|------|
| Added Timing Diagram | 4 |

| Changes from Original (AUGUST 2023) to REV.A | Page |
|---|------|
| Changed from product preview to production data | All |

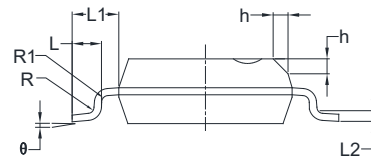
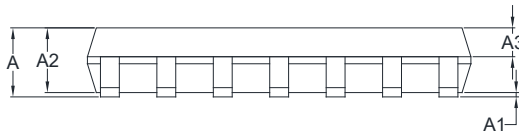
PACKAGE INFORMATION

PACKAGE OUTLINE DIMENSIONS

SOIC-14



RECOMMENDED LAND PATTERN (Unit: mm)



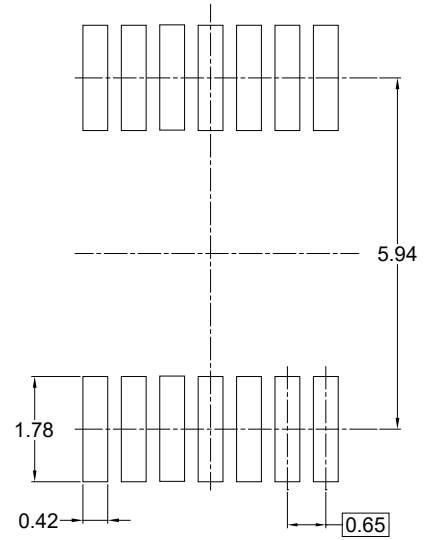
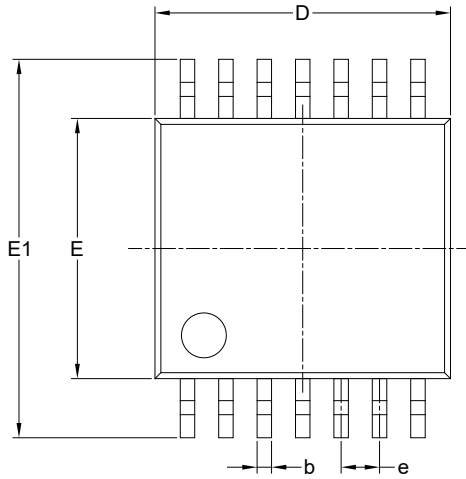
| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|------------------------------|------|-------------------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.35 | 1.75 | 0.053 | 0.069 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| A2 | 1.25 | 1.65 | 0.049 | 0.065 |
| A3 | 0.55 | 0.75 | 0.022 | 0.030 |
| b | 0.36 | 0.49 | 0.014 | 0.019 |
| D | 8.53 | 8.73 | 0.336 | 0.344 |
| E | 5.80 | 6.20 | 0.228 | 0.244 |
| E1 | 3.80 | 4.00 | 0.150 | 0.157 |
| e | 1.27 BSC | | 0.050 BSC | |
| L | 0.45 | 0.80 | 0.018 | 0.032 |
| L1 | 1.04 REF | | 0.040 REF | |
| L2 | 0.25 BSC | | 0.01 BSC | |
| R | 0.07 | | 0.003 | |
| R1 | 0.07 | | 0.003 | |
| h | 0.30 | 0.50 | 0.012 | 0.020 |
| θ | 0° | 8° | 0° | 8° |

NOTES:

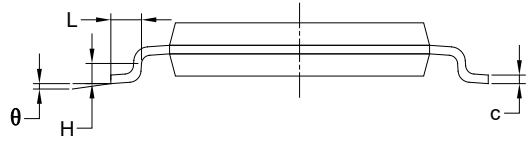
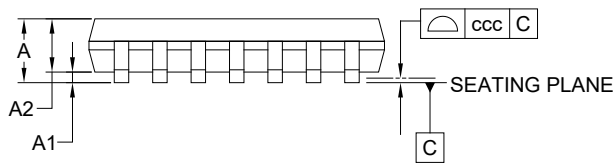
1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

TSSOP-14



RECOMMENDED LAND PATTERN (Unit: mm)



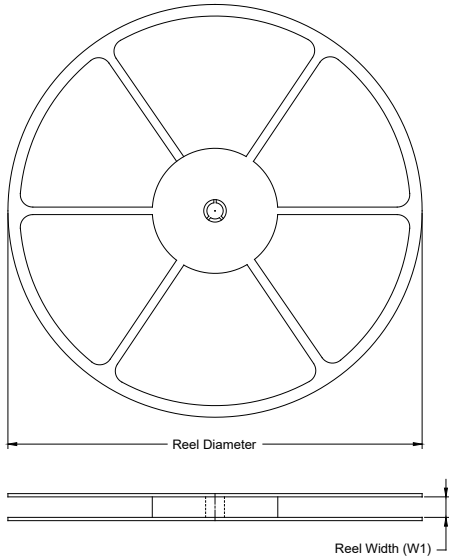
| Symbol | Dimensions In Millimeters | | |
|--------|---------------------------|-----|-------|
| | MIN | NOM | MAX |
| A | - | - | 1.200 |
| A1 | 0.050 | - | 0.150 |
| A2 | 0.800 | - | 1.050 |
| b | 0.190 | - | 0.300 |
| c | 0.090 | - | 0.200 |
| D | 4.860 | - | 5.100 |
| E | 4.300 | - | 4.500 |
| E1 | 6.200 | - | 6.600 |
| e | 0.650 BSC | | |
| L | 0.450 | - | 0.750 |
| H | 0.250 TYP | | |
| theta | 0° | - | 8° |
| ccc | 0.100 | | |

NOTES:

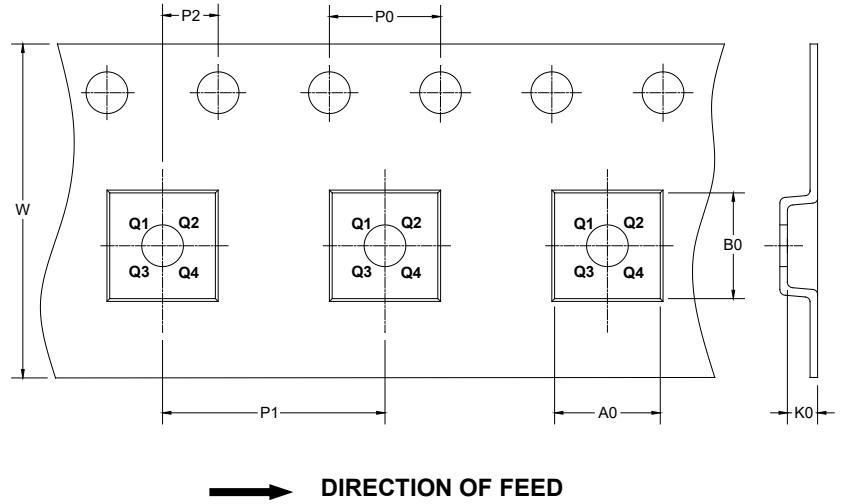
1. This drawing is subject to change without notice.
2. The dimensions do not include mold flashes, protrusions or gate burrs.
3. Reference JEDEC MO-153.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

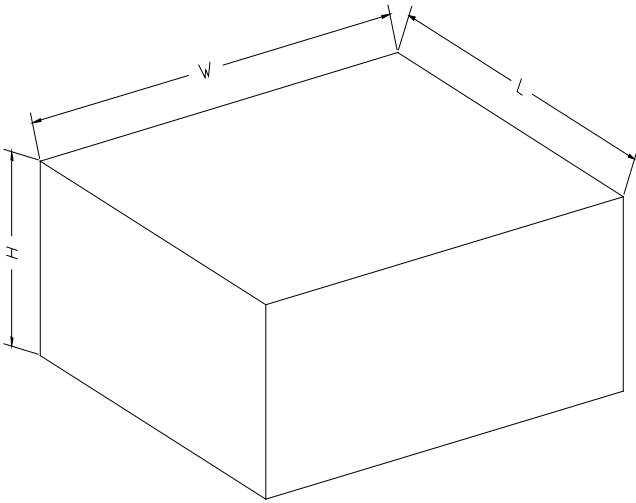
KEY PARAMETER LIST OF TAPE AND REEL

| Package Type | Reel Diameter | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P0 (mm) | P1 (mm) | P2 (mm) | W (mm) | Pin1 Quadrant |
|--------------|---------------|--------------------|---------|---------|---------|---------|---------|---------|--------|---------------|
| SOIC-14 | 13" | 16.4 | 6.60 | 9.30 | 2.10 | 4.0 | 8.0 | 2.0 | 16.0 | Q1 |
| TSSOP-14 | 13" | 12.4 | 6.80 | 5.40 | 1.50 | 4.0 | 8.0 | 2.0 | 12.0 | Q1 |

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PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

| Reel Type | Length (mm) | Width (mm) | Height (mm) | Pizza/Carton |
|-----------|-------------|------------|-------------|--------------|
| 13" | 386 | 280 | 370 | 5 |

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